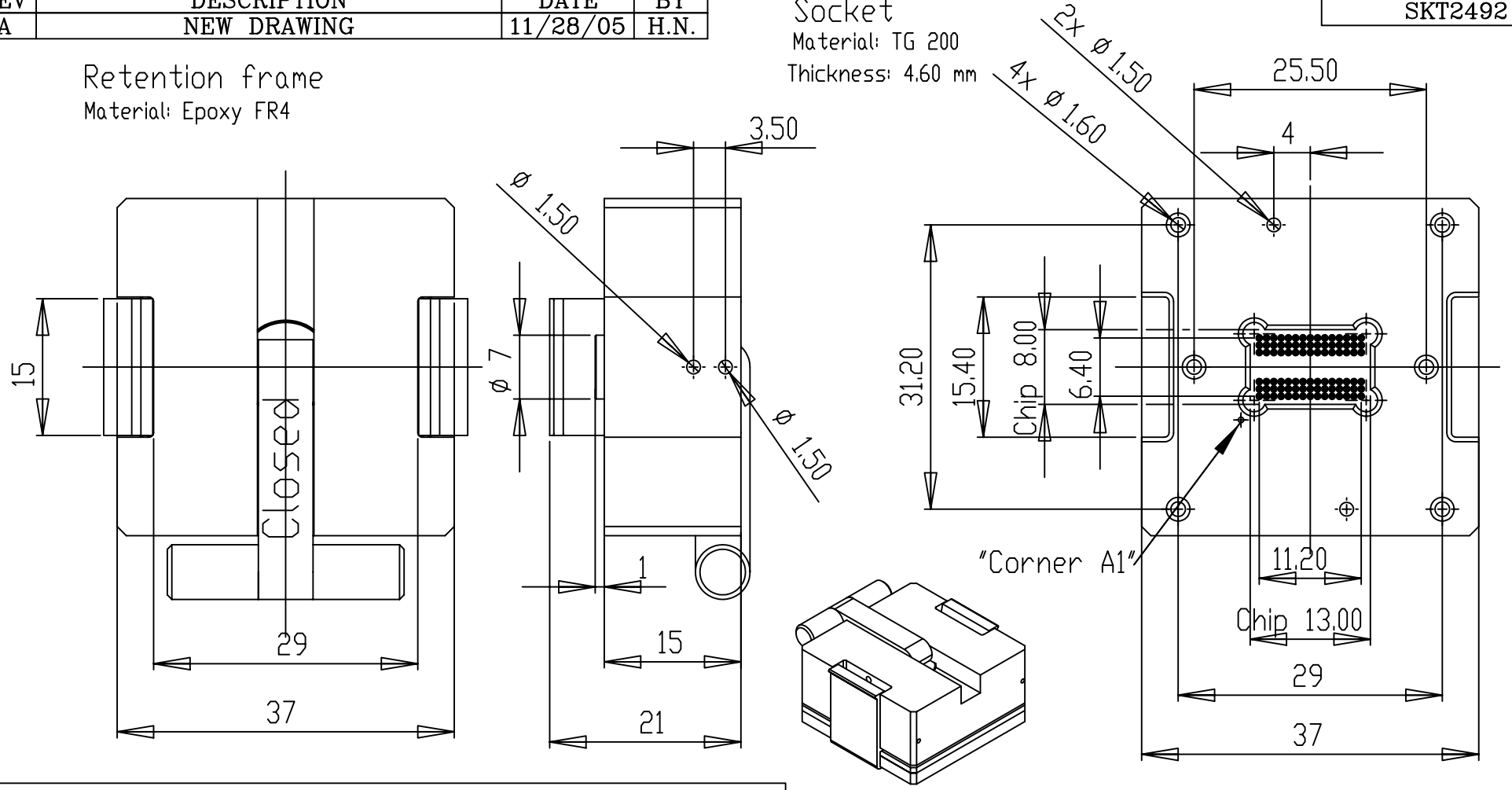
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	11/28/05	H.N.

SKT2492

Retention frame
Material: Epoxy FR4

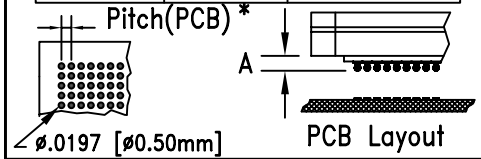
Socket
Material: TG 200
Thickness: 4.60 mm



RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE

REGULAR SMT STYLE	RAISED SMT STYLE	SPECIAL RAISED SMT STYLE
XX = (-SM)	XX = (-SR)	XX = (-SC)
YY = (-30)	YY = (-29)	YY = (-28)

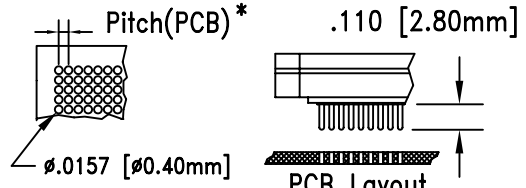


-30= standard SMT ("A" = .0236 [0.60mm])
-29= raised SMT ("A" = .110 [2.80mm])
-28= Special raised SMT ("A" = .177 [4.50mm])

BALL DIAMETER FOR:
-30(SM) = .0157 [0.40mm] TO .0217 [0.55mm]
-29(SR) = .0157 [0.40mm] TO .0217 [0.55mm]
-28(SC) = .0157 [0.40mm] TO .0217 [0.55mm]

BALL HEIGHT FOR:
-30(SM) = .0098 [0.25mm] TO .0177 [0.45mm]
-29(SR) = .0098 [0.25mm] TO .0177 [0.45mm]
-28(SC) = .0098 [0.25mm] TO .0177 [0.45mm]

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET)
YY = (-70)



PIN DIAMETER FOR:
-70(ET) = .0114 [0.29mm]

* All Dimmensions Are Nominal For A .0315 [0.80mm] Pitch BGA Package

PACKAGE SPECIFICATIONS

PIN COUNT	=	90
LEAD PITCH	=	0.80mm
GRID SIZE	=	9X15
PACKAGE SIZE	=	8.00X13.00mm

ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED

Emulation Technology, Inc.
VLSI and SMT ADAPTERS and ACCESSORIES
2344 Walsh Avenue, Bldg.F
Santa Clara, Ca 95051
TEL:(408)982-0660
FAX:(408)982-0664

SHEET:	DATE:	REVISION:	
1 OF 1	11/28/05	A	ASSEMBLY DRAWING

CHECKED:	DRAWN:	ITEM:
Perry Munroe	Huy Nguyen	S-MBQ-15-090-XX

Scale N/A	DO NOT SCALE DRAWING	DESCRIPTION:
		BPQ-090-6BG015-YY